

L Number	Hits	Search Text	DB	Time stamp
1	399	smart near5 cut	USPAT; US-PGPUB	2004/02/02 12:51
2	50763	substrate near3 bond\$3	USPAT; US-PGPUB	2004/02/02 12:52
3	50987	(smart near5 cut) (substrate near3 bond\$3)	USPAT; US-PGPUB	2004/02/02 11:52
4	11479	((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))	USPAT; US-PGPUB	2004/02/02 12:52
5	2062	((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (pressure near5 (fluid gas air))	USPAT; US-PGPUB	2004/02/02 12:52
6	893	((((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (pressure near5 (fluid gas air))) and (chip die dice)	USPAT; US-PGPUB	2004/02/02 11:55
7	355	(((((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (pressure near5 (fluid gas air))) and (chip die dice)) and (implant\$3 dop\$4))	USPAT; US-PGPUB	2004/02/02 12:53
8	204	(((((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (pressure near5 (fluid gas air))) and (chip die dice)) and (implant\$3 dop\$4)) and (remov\$3 same separat\$3)	USPAT; US-PGPUB	2004/02/02 11:57
9	24	(((((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (pressure near5 (fluid gas air))) and (chip die dice)) and (implant\$3 dop\$4)) and (remov\$3 same separat\$3 same chip)	USPAT; US-PGPUB	2004/02/02 11:57
10	35	smart near5 cut	EPO; JPO; DERWENT; IBM_TDB	2004/02/02 12:51
11	27230	substrate near3 bond\$3	EPO; JPO; DERWENT; IBM_TDB	2004/02/02 12:52
12	27262	(smart near5 cut) (substrate near3 bond\$3)	EPO; JPO; DERWENT; IBM_TDB	2004/02/02 12:52
14	503	((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))	EPO; JPO; DERWENT; IBM_TDB	2004/02/02 12:52
15	9	((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (pressure near5 (fluid gas air))	EPO; JPO; DERWENT; IBM_TDB	2004/02/02 12:53
16	37	((smart near5 cut) (substrate near3 bond\$3)) and (separat\$3 near5 (film layer))) and (implant\$3 dop\$4)	EPO; JPO; DERWENT; IBM_TDB	2004/02/02 12:53